

立威科技股份有限公司 Attend Technology Inc.

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SPECIFICATION AND PERFORMANCE

Series	217D-AG11	File	217D-AG11	Date	2024/05/30
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Scope:

This specification covers the requirements for product performance, test methods and quality assurance provisions of 217D-AG11

Performance and Descriptions:

The product is designed to meet the electrical, mechanical and environmental performance requirements specification. Unless otherwise specified, all tests are performed at ambient environmental conditions.

RoHS:

All material in according with the RoHS environment related substances list controlled.

	MATERIALS			
NO.	PART NAME	DESCRIPTION		
1	HOUSING	Polyamide 9T (PA9T), UL94V-0, black or equal		
2	CONTACT	Chromium Copper C18400, 30u" min. gold plating on contact area, 60u" min. tin plating on solder tails, 80u" min. nickel under plating over all		
3	SHELL	Stainless Steel SUS304, 50u" min. nickel plating over all		
4	MID PLATE	Stainless Steel SUS301, 50u" min. nickel plating over all		
5	CAP	LCP E130i, UL94V-0, BLACK or equal		

RATING		
Rated Voltage	48V	
Rated Current	5A	
Operating Temperature	-40°C to +85°C	
Storage Temperature	-40°C to +85°C	
Durability	10,000cycles	

ELECTRICAL			
Item	Requirement	Test Condition	
Low level contact resistance	40 m Ω Max initial for VBUS, GND and all other contacts. 50 m Ω Max. after test	The low level contact resistance (LLCR) measurement is made across the plug and receptacle mated contacts and does not include any internal paddle cards or substrates of the plug or receptacle. The test boards shall be provided with the connectors to be tested. Measure at 20 mV (max) open circuit at 100 mA. EIA-364-23	





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Insulation resistance	100MΩ Min.	Mated or un-mated connector, apply 250 Volts DC between adjacent terminal or ground. EIA-364-21
Dielectric withstanding voltage	100VAC no disruptive discharge	Mated connector, apply 100V AC(RMS) for 1minute between adjacent terminal or ground, Leakage current: 5mA Max. EIA-364-20

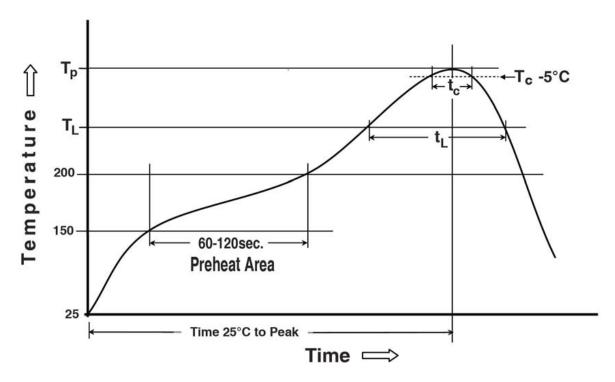
MECHANICAL			
Item	Requirement	Test Condition	
Durability	 No evidence of physical damage. The electrical performances should meet the spec specified. 	Mate and un-mate samples for 10,000 cycles at maximum rate of 500 cycles per hour. EIA-364-09	
Insertion force and extraction force	 Insertion force: 5N~20N Extraction force: 8N~20N after the durability test (10,000 cycles): 6N~20N. 	Measure the force required to mate connector, At a maximum rate of 12.5mm (0.492") per minute. EIA-364-13	

ENVIRONMENTAL			
Item	Requirement	Test Condition	
Humidity test	 No evidence of damage. The electrical performances should meet the spec specified. 	25~65°C in temperature and 90~95%RH for 48 hours. After test connector shall be left alone for 1 to 2 hours in a room ambient	
Temperature life	 No evidence of damage. The electrical performances should meet the spec specified. 	The specimens shall be subjected to a temperature of 85°C for 120 hours, then placed in ambient temperature for 3 hours. EIA-364-17	
Thermal shock	 No evidence of damage. The electrical performances should meet the spec specified. 	The specimens shall be subjected to a temperature of 10 cycles, -55°C for 30 minutes, 85°C for 30 minutes, then placed in ambient temperature for more than 1~2 hours EIA-364-32	
Salt spray	No evidence of damage. The electrical performances should meet the spec specified.	Subject mated and unmated connectors should be tested according to the condition listed below: Salt concentration: 5% Temperature: 35±1°C Humidity: 95 ~ 98% (R.H.) PH Value: 6.5 ~ 7.2 Duration: 48 hours EIA-364-26	



SOLDER ABILITY			
Item	Requirement	Test Condition	
Solder ability	95% of immersed area must show no voids, pin holes	The termination should be 95% covered with new continuous solder coating Solder temperature: 255±5°C Test time: 5±1 seconds, (Per EIA-364-71)	
Resistance to soldering heat	No melting, cracks or functional damage allowed	Preheating temperature: 150 ~ 200°C, 60~180 seconds Liquidus temperature (TL): 217°C, 60~150 seconds Peak temperature: 260°C Time within 5°C of peak temperature (Tc): 255°C, 30seconds	

Reflow Profile



Preheating temperature: 150 \sim 200°C, 60 \sim 180 seconds Liquidus temperature (TL): 217°C, 60 \sim 150 seconds

Peak temperature: 260°C

Time within 5 °C of peak temperature (Tc): 255°C, 30seconds

